1-1747147-5 V ACTIVE

Dynamic Series | Dynamic DZ 5200 Series

TE Internal #: 1-1747147-5

PCB Mount Receptacle, Vertical, Board-to-Board, 5 Position, 5.08 mm [.2 in] Centerline, Gold (Au), Through Hole - Solder, Dynamic

DZ 5200 Series

View on TE.com >

connectivity

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 5
Number of Rows: 1

Features

Product Type Features

PCB Connector Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

Configuration Features

Board-to-Board Configuration	Perpendicular
PCB Mount Orientation	Vertical
Number of Positions	5
Number of Rows	1

Body Features

Primary Product Color	Black

Contact Features

Contact Mating Area Plating Material Thickness	.2 μm[8 μin]
Contact Mating Area Plating Material	Gold (Au)
Contact Type	Receptacle
Contact Current Rating (Max)	20 A



Termination Features

Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
PCB Mount Retention Type	Retention Leg
PCB Mount Retention	With
PCB Mount Alignment	Without
Mating Alignment	With
Housing Features	
Housing Material	PBT GF
Centerline (Pitch)	5.08 mm[.2 in]
Dimensions	
PCB Thickness (Recommended)	1.6 mm[.063 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Power
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box, Tube

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.



Solder Process Capability

Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Dynamic DZ 5200 Series



Customers Also Bought





gold or tin plated









Documents

CAD Files

Customer View Model

ENG_CVM_CVM_1-1747147-5_C.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-1747147-5_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-1747147-5_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Product Specification

Japanese